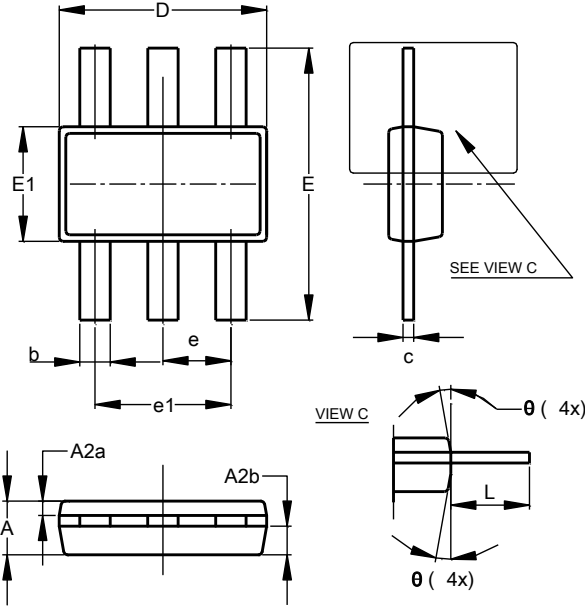


**Package Outline Dimensions**

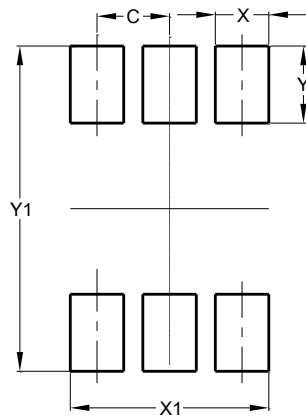
**TSOT26F**



TSOT26F			
Dim	Min	Max	Typ
A	0.700	0.800	0.750
A2a	0.325	0.375	0.350
A2b	0.375	0.425	0.400
b	0.425	0.475	0.450
c	0.150	0.200	0.175
D	2.850	2.950	2.900
E	3.750	3.850	3.800
E1	1.550	1.650	1.600
e	0.950 BSC		
e1	1.900 BSC		
L	1.100 BSC		
θ	4°	12°	10°
<b>All Dimensions in mm</b>			

**Suggested Pad Layout**

**TSOT26F**



Dimensions	Value (in mm)
C	0.950
X	0.700
X1	2.600
Y	1.000
Y1	4.220

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.